

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITORS

Low Profile Series

0402 to 1210 Sizes

X7R, X5R & Y5V Dielectrics

Halogen Free & RoHS Compliance



*Contents in this sheet are subject to change without prior notice.



1. DESCRIPTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC TT series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R, X5R and Y5V are used for this series product.

2. FEATURES

- a. Standard size with thin thickness.
- b. Small size with high capacitance.
- c. Capacitor with lead-free termination (pure Tin).

3. APPLICATIONS

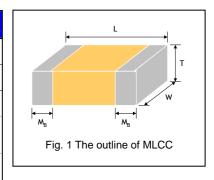
- a. For LCD panels.
- b. For PCMCA cards.
- c. For IC packaging and modules.
- d. Any thickness concerned products.

4. HOW TO ORDER

<u>II</u>	<u>15</u>	<u>X</u>	<u>475</u>	<u>M</u>	<u>6R3</u>	<u>C</u>	I
<u>Series</u>	Size	Dielectric	Capacitance	Tolerance	Rated voltage	<u>Termination</u>	<u>Packaging</u>
TT=Low profile	15 =0402 (1005) 18 =0603 (1608) 21 =0805 (2012) 31 =1206 (3216) 32 =1210 (3225)	X =X5R F =Y5V	Two significant digits followed by no. of zeros. And R is in place of decimal point.	K=±10% M=±20% Z=-20/+80%	Two significant digits followed by no. of zeros. And R is in place of decimal point.	C =Cu/Ni/Sn	T=7" reeled G=13" reeled
		COPYRIGHT	eg.: PASSIVE SYS 475=47x10 ⁵ =4,700,000pF =4.7µF	DEN COLO	6R3=6.3 VDC 100=10 VDC 160=16 VDC 250=25 VDC 500=50 VDC 101=100 VDC		

5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Sy	mbol	M _B (mm)
0402 (1005)	1.00±0.2	0.5±0.2	0.30±0.03	L	0.25±0.10
0603 (1608)	1.6+0.15/-0.10	0.8+0.15/-0.10	0.50±0.10	Н	0.40±0.15
0805 (2012)	2.00±0.20	1.25±0.20	0.85±0.10	Т	0.50±0.20
1206 (2216)	2 20 . 0 20	1.60±0.20	0.85±0.10	Т	0.60.0.20
1206 (3216)	3.20±0.20	1.60±0.20	1.15±0.15	J	0.60±0.20
1010 (2005)	2 20 . 0 20	2.50.0.20	0.85±0.10	Т	0.75.0.25
1210 (3225)	3.20±0.30	2.50±0.20	2 00+0 20	K	0.75±0.25



6. GENERAL ELECTRICAL DATA

Dielectric	X7R	X5R	Y5V					
Size		0402, 0603, 0805, 1206, 1210						
Capacitance range*	1μF to 10μF	1μF to 10μF 0.22μF to 22μF						
Capacitance tolerance**	K (±10%)	K (±10%), M (±20%)						
Rated voltage (WVDC)	10V, 16V, 25V, 50V, 100V	6.3V, 10V, 16V, 25V	10V, 16V, 25V, 50V					
Operating temperature	-55 to +125℃	-55 to +85℃	-25 to +85℃					
Capacitance characteristic	±15% +30/-80%							
Termination	JYM LA	Ni/Sn (lead-free termination)						

^{*} Measured at 1.0±0.2Vrms, 1.0kHz±10%, 30~70% related humidity, 25°C ambient temperature for X7R, X5R and at 20°C for Y5V.

^{**} Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.



^{*} Reflow soldering process only is recommended.



7. CAPACITANCE RANGE

7-1 X7R dielectric

	Dielectric						X7R					
	Size	0805 1206			06	1210						
Rated voltage (VDC)		10	16	25	50	10	16	25	50	10	16	100
	1.0µF (105)							Т				
0	1.5µF (155)											
Capacitance	2.2µF (225)		Т	Т					Т			K
ita	3.3µF (335)											
Jac	4.7μF (475)	Т						Т				
Sag	6.8µF (685)											
	10μF (106)					Т						
	22μF (226)											

7-2 X5R dielectric

	Dielectric									K5R								
	Size		0402		06	03		08	05				1206				1210	
Rate	ed voltage (VDC)	6.3	10	25	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
	0.22uF (224)			L	Н	Н												
	0.47uF (474)	L		L														
	1.0µF (105)	L			Н	Н		Т	Т	Т		Т	Т	Т				
မွ	1.5µF (155)							Т	Т			Т	Т	Т				
Capacitance	2.2µF (225)	L					I	,_T		Т		Т	Т	Т	Т			
cit	3.3µF (335)						K-7		13	7		Т	Т	Т		Т		
ъ Б	4.7µF (475)	L			Н	136	()T	T	7-7	7 £		Т	Т	Т		Т		
ပိ	6.8µF (685)				/\	THE SE	比	队 4	$4 \times$	1	110							
	10µF (106)				K	X		17大人	U 18		J	J/T		Т		Т		Т
	22uF (226)				/ Jym	12	ΛŤ	Т	3/	%	177	14	Т				Т	
	47uF (476)				77/4/	4					> Tc	13						
7-3	Y5V dielectri	ic				#/		S	Δ	J	111							

7-3 Y5V dielectric

	Dielectric						Y5V				
	Size		0	805			12	.06		12	10
Rate	ed voltage (VDC)	10	16	25	50	10	16	25	50	10	16
	1.0µF (105)		1		Ţ			25			
4	1.5µF (155)			0/1	6-1		40	11.			
ဗ	2.2µF (225)		Т	3/0	Chn	oloTol (D.T.	T			
<u>ia</u>	3.3µF (335)	Т		2111	/En	01081	TOM ALL				
Capacitance	4.7μF (475)	Т	Т		34/1/10/10	CA CUBBUS	7/104,				
Зар	6.8µF (685)				.070	a) CAULO					
)	10μF (106)	Т				Т				Т	
	22µF (226)										

8. PACKAGING STYLE AND QUANTITY

Cina	This large May (may	VC make al	7" reel				
Size	Thickness Max (mm	/Symbol	Paper tape	Plastic tape			
0402 (1005)	0.33	L	15k	-			
0603 (1608)	0.60	Н	4k	-			
0805 (2012)	0.95	Т	4k	-			
4000 (0040)	0.95	Т	4k	-			
1206 (3216)	1.30	J	-	3k			
4040 (0005)	0.95	Т	-	3k			
1210 (3225)	2.00	K	-	1k			

Unit: pieces

9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition	Requirements		
1.	Visual and Mechanical		* No remarkable defect. * Dimensions to conform to individual specification sheet.		
	Capacitance Q/ D.F. (Dissipation Factor)	* Test temp.: Room Temperature. Cap≤10µF, 1.0±0.2Vrms, 1kHz±10% Cap>10µF, 0.5±0.2Vrms, 120Hz±20%** ** Test condition: 0.5±0.2Vrms · 1KHz±10% TT18X ≥ 475(10V) , TT15X series *Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp .	* Shall not exceed the limits given in the detailed spec. X7R/X5R: Rated vol. 100V 55% 50V, 25V, 16V, 10V ≤10% 6.3V Y5V: Rated vol. 50V 27% 25V 49% 16V/10V 512.5%		
4.	Dielectric Strength	* To apply voltage: 250% rated voltage. * Duration: 1 to 5 sec. * Charge and discharge current less than 50mA.	* No evidence of damage or flash over during test.		
5.	Insulation Resistance	* Test temp.: Room Temperature. * To apply rated voltage for max. 120 sec.	≥10GΩ or RxC≥100Ω-F whichever is smaller.		
6.	Temperature Coefficient	With no electrical load. T.C. Operating Temp X7R -55~125℃ at 25℃ X5R -55~85℃ at 25℃ Y5V -25~85℃ at 20℃ *Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24± 2 hrs at room temp.	T.C. Capacitance Change X7R Within ±15% X5R Within ±15% Y5V Within +30%/-80%		
		0402 0603 Cap<1μF: 1V Cap=1μF: 0.5V** 0402B224-16V: 0.5V 0402B474-10V: 0.5V 0402B474-10V: 0.5V 0402E475M6R3: 0.5V 1μF <cap<10μf: **0402b105m6r3v:="" 0.1v="" 0.2v="" 0.5v="" 0805="" 10μf<cap≤10μf:="" 1206="" 1210="" 1v="" cap="" cap<10μf:="" cap≥10μf:="">10μF< 0.5V Cap>10μF: 0.5V Cap>10μF: 0.5V Cap>10μF: 0.5V Cap>10μF: 0.5V Cap>10μF: 0.5V</cap<10μf:>	EANCE US STATE OF THE STATE OF		
7.	Adhesive Strength of Termination	* Pressurizing force : 5N (≤0603) and 10N (>0603) * Test time: 10±1 sec.	No remarkable damage or removal of the terminations.		
8.	Vibration Resistance	* Vibration frequency: 10~55 Hz/min. * Total amplitude: 1.5mm * Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap./DF(Q) Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	* No remarkable damage. * Cap change and Q/D.F.: To meet initial spec.		
9.	Solderability	* Solder temperature: 235±5°C * Dipping time: 2±0.5 sec.	95% min. coverage of all metalized area.		
10.	Bending Test	* The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs.	intil * Can change :		
11.	Resistance to Soldering Heat	* Solder temperature: 260±5°C * Dipping time: 10±1 sec * Preheating: 120 to 150°C for 1 minute before imme rse the capacitor in a eutectic solder. *Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. *Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	* 25% max. leaching on each edge.		

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.

ASC_ Low Profile_(TT)_009R_AS

Page 5 of 9

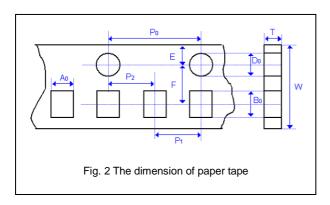


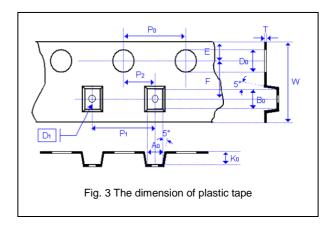
No.	Item	Test Condition			Requirements
12.	Temperature Cycle	* Conduct the five cycles according to the time.		* No remarkable da * Cap change :	
		Step Temp. (°C)	Time (min.)	X7R/X5R: within	
		1 Min. operating temp. +0/-3	30±3	Y5V: within ±20%	
		2 Room temp.	2~3	* Q/D.F., I.R. and d	dielectric strength: To meet initial requirements.
		3 Max. operating temp. +3/-0	30±3		
		4 Room temp.	2~3		
		* Before initial measurement (Class II only at 150℃ for 1hr then set for 24±2 hrs at ro	oom temp.		
		* Cap. / DF(Q) / I.R. Measurement to be n			
		at 150℃ for 1hr then set for 24±2 hrs at ro	oom temp.	***************************************	
3.	Humidity	* Test temp.: 40±2℃		*No remarkable da *Cap change: X7	image. 7R/X5R: within ±25%
	(Damp Heat)	* Humidity: 90~95% RH			5V: within ±30%; 6.3V, within +30/-40%
	Steady State	* Test time: 500+24/-0hrs.		*Q/D.F. value:	
		* Before initial measurement (Class II only	/): To apply de-aging	X7R/X5R:	
		at 150℃ for 1hr then set for 24±2 hrs at ro	oom temp.	Rated vol.	D.F.
		* Cap. / DF(Q) / I.R. Measurement to be n	nade after de-aging	100V	≤7.5%
		at 150℃ for 1hr then set for 24±2 hrs at ro	oom temp.	25V, 16V	≤15%
			•	10V	≤20%
				50V, 6.3V	≤30%
			1 -	Y5V:	
			公有 1	Rated vol.	D.F.
		は進		50V	≤10%
		N. T. T.	"比"的"(4)	25V	≤15%
			XX IX III 1	16V, 10V	≤20%
		TVm LX		*I.R.: 1GΩ or RxC≧	10 Ω-F whichever is smaller.
14.	Humidity (Damp Heat)	* Test temp.: 40±2°C * Humidity: 90~95%RH			mage. 'R/X5R: within ±25% 5V: within ±30%; 6.3V, within +30/-40%
	Load	* Test time: 500+24/-0 hrs.			5V. Within 13070, 0.3V, Within 1307-4070
	Loau			*Q/D.F. value:	
		* To apply voltage: Rated voltage. * Before initial measurement (Class II only	SIVE SYSTEM AL	[™] X7R/X5R:	3
		at 150°C for 1hr then set for 24±2 hrs at ro	, ,,,	Rated vol.	D.F.
		* Cap. / DF(Q) / I.R. Measurement to be n	•	100V	≤7.5%
			3 3	25V, 16V	≤15%
		at 150℃ for 1hr then set for 24±2 hrs at i	oom temp.	10V	≤20%
		A/Cu.	Thology (50V, 6.3V	≤30%
		7/1/TE	7/1/2	Y5V:	
		1.20	PHNOLOGY CORPOR	Rated vol.	D.F.
			25001 COIII 01	50V	≤10%
				25V	≤15%
				16V, 10V	≤20%
				*I.R.: 500MΩ or R	$xC \ge 5 \Omega$ -F whichever is smaller.
5.	High	* Test temp. :		*No remarkable da	•
	Temperature	NP0, X7R/X7E: 125±3℃ X5R, Y5V: 85±3℃			'R/X5R: within ±25% 5V: within ±30%; 6.3V, within +30/-40%
	Load	* Test time: 1000+24/-0 hrs.		*Q/D.F. value:	5V. WILLIII ±30 /6, 0.5 V, WILLIII +30/-40 /6
	(Endurance)	* To apply voltage: 150% of rated voltage.			
	,	**100% of rated voltage for below range.		X7R/X5R:	2.5
		Size Dielectric Rated voltage	Capacitance range	Rated vol.	D.F.
		TT15 X5R 6.3V	C≧1.0µF	100V	≤7.5%
		TT18 Y5V 6.3V,10V	C≧ 1.0µF	25V, 16V	≤15%
		TT21 Y5V 6.3V	C≧10µF	10V	≤20%
		X5R/X/R/X6S ≦10V	C≥10µF	50V, 6.3V	≤30%
		TT31 Y5V 6.3V	C≧22µF	Y5V:	
		*Before initial measurement (Class II only): To apply de-aging	Rated vol.	D.F.
		at 150℃ for 1hr then set for 24±2 hrs at ro		50V	≤10%
		* Cap. / DF(Q) / I.R. Measurement to ©r d	e-aging at 150℃ for	25V	≤15%
	l	1hr then set for 24±2 hrs at room temp.		16V, 10V	≤20%
		•		:	•

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.

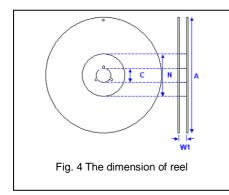
APPENDIXES

■ Tape & reel dimensions



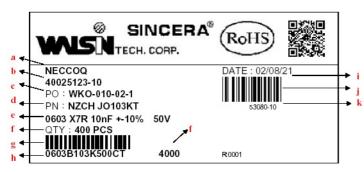


Size	0402	0603	0805	12	06	12	210
Thickness	L	Н	Т	_ T	J	Т	K
A_0	0.70 +/-0.20	1.05 +/-0.30	1.50 +/-0.20	1.90 +/-0.50	< 2.00	< 3.05	< 3.05
B ₀	1.20 +/-0.20	1.80 +/-0.30	2.30 +/-0.20	3.50 +/-0.50	< 3.70	< 3.80	< 3.80
Т	≦0.80	≦1.20	≦1.20	≦1.20	0.23 +/-0.1	0.23 +/-0.1	0.23 +/-0.1
K ₀	-	1777	-	- \\	< 2.00	< 1.50	< 2.50
w	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30
Po	4.00 +/-0.10	4.00 +/-0.10	PASS 4.00 SYSTEM	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
10xP ₀	40.00 +/-0.10	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20
P ₁	2.00 +/-0.05	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
P ₂	2.00 +/-0.05	2.00 +/-0.05	2.00	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05
D ₀	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0 GV	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0
D ₁	-	-	-	-	1.00 +/-0.10	1.00 +/-0.10	1.00 +/-0.10
E	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10
F	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05



Size	040	0402, 0603, 0805, 1206, 1210						
Reel size	7"	10"	13"					
С	13.0±0.5	13.0±0.5	13.0±0.5					
W ₁	10.0±1.5	10.0±1.5	10.0±1.5					
Α	178.0±2.0	250.0±2.0	330.0±2.0					
N	60.0+1.0/-0	50 min	50 min					

■ Example of customer label

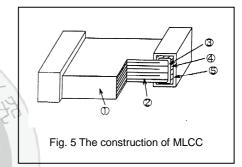


^{*}Customized label is available upon request

- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

No.	Nam	пе	X7R, X5R, Y5V
1	Ceramic r	material	BaTiO₃ based
2	Inner ele	ctrode	Ni ₂ (2)
3		Inner layer	Cu
4	Termination	Middle layer	Ni
(5)		Outer layer	Sn (Matt)



PASSIVE SYSTEM ALLIANCE

Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%, related humidity conditions; MSL Level 1.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.

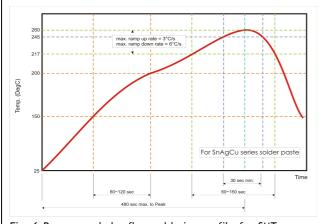


Fig. 6 Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.

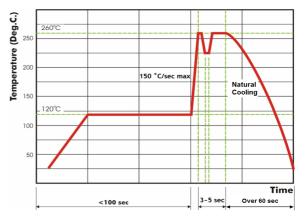


Fig. 7 Recommended wave soldering profile for SMT process with SnAgCu series solder.



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